

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S81	210	361/766.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/20 14:30
S82	36	S81 and 361/765.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/20 14:31
S83	1	S82 and 361/761.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/20 15:26
S84	0	cnnecting adj component	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/20 15:26
S85	0	cnnecting adj component	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/20 15:27
S86	106	flexible adj conducting adj wire	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/20 15:28
S87	1	S86 and extended adj portion	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/20 15:28
S88	0	("2006/0268590").URPN.	USPAT	OR	ON	2007/09/20 15:28
S89	148	361/141.ccls.	USPAT	OR	ON	2007/09/20 15:35

## EAST Search History

S90	1	"525" and flexible adj conducting adj wire	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/20 15:28
S91	0	S89 and flexible adj conducting adj wire	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/20 15:29
S92	0	S89 and flexible adj conducting	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/20 15:51
S93	28	flexible adj conducting adj wire	USPAT	OR	ON	2007/09/20 15:36
S94	0	S93 and Rectifier adj diode	USPAT	OR	ON	2007/09/20 15:38
S95	4914	Rectifier adj diode	USPAT	OR	ON	2007/09/20 15:36
S96	34	S95 and electric adj generator	USPAT	OR	ON	2007/09/20 15:37
S97	0	S96 and flexible adj conducting adj wire	USPAT	OR	ON	2007/09/20 15:37
S98	0	flexible adj conducting adj wire and Rectifier adj diode	USPAT	OR	ON	2007/09/20 15:39
S99	3	flexible adj conducting and Rectifier adj diode	USPAT	OR	ON	2007/09/20 15:41
S10 0	3	"6,455,929"	USPAT	OR	ON	2007/09/20 15:41
S10 1	15	("20050082692"   "3869703"   "4256973"   "4586075"   "4942139"   "5005069"   "5424594"   "6060776"   "6160309"   "6310791"   "6331730"   "6455929"   "6476480"   "6667545").PN. OR ("7009223").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/09/20 15:45
S10 2	220690	semiconductor adj device	US-PGPUB; USPAT; USOCR	OR	ON	2007/09/20 15:46
S10 3	4300	S102 and cup	US-PGPUB; USPAT; USOCR	OR	ON	2007/09/20 15:46
S10 4	2082	S103 and lead	US-PGPUB; USPAT; USOCR	OR	ON	2007/09/20 15:46

## EAST Search History

S10 5	8	S104 and conducting adj wire	US-PGPUB; USPAT; USOCR	OR	ON	2007/09/20 15:50
S10 6	218358	main adj body	US-PGPUB; USPAT; USOCR	OR	ON	2007/09/20 15:50
S10 7	2	S106 and flexible adj conducting adj wire	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/20 15:52
S10 8	1	("3076288").URPN.	USPAT	OR	ON	2007/09/20 15:51
S10 9	49	S106 and flexible adj conducting	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/20 15:54
S11 0	106	flexible adj conducting adj wire	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/20 15:54
S11 1	8	S110 and welding	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/20 15:58
S11 2	3	"11113151"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/20 15:58
S11 3	2	("20050011633"   "20050235494"). PN. OR ("7047639").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/09/20 17:08
S11 4	1	"20040142730"	US-PGPUB; USPAT; USOCR	OR	ON	2007/09/20 17:11
S11 5	11	"3675095"	US-PGPUB; USPAT; USOCR	OR	ON	2007/09/20 17:11

## EAST Search History

S11 6	11	"4339668"	US-PGPUB; USPAT; USOCR	OR	ON	2007/09/20 17:12
S11 7	2	("4339668").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/09/20 17:12
S11 8	6	("6266227").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/09/21 13:45
S11 9	17	"6266227"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/20 17:13
S12 0	462274	circuit adj board	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/21 13:46
S12 1	123831	S120 and substrate	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/21 13:46
S12 2	7558	S121 and insulating adj substrate	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/21 13:46
S12 3	2183	S122 and capacitor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/21 13:46
S12 4	651	S123 and conductive adj layer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/21 13:47

## EAST Search History

S12 5	481	S124 and hole	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/21 13:47
S12 6	349	S125 and electrodes	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/21 13:47
S12 7	0	S126 and linear adj conductive adj layer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/21 13:48
S12 8	349	S126 and conductive adj layer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/21 13:48
S12 9	349	S128 and insulating adj substrate	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/21 13:49
S13 0	349	S129 and conductive adj layer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/21 13:49
S13 1	349	S130 and capacitor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/21 13:50
S13 2	4	S131 and single adj layer adj circuit	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/21 13:50

## EAST Search History

S13 3	0	S132 and plurality adj layer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/21 13:51
S13 4	4	S132 and layers	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/21 13:56
S13 5	29	"6,370,012"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/21 14:53
S13 6	462274	circuit adj board	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/21 14:54
S13 7	7558	S136 and insulating adj substrate	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/21 14:54
S13 8	2183	S137 and capacitor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/21 14:54
S13 9	2183	S138 and insulating adj substrate	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/21 14:55
S14 0	1427	S139 and electrodes	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/21 14:55

## EAST Search History

S14 1	62	S140 and capacitor adj structure	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/21 14:56
S14 2	24	S141 and conductive adj layer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/21 15:39
S14 3	8	11/031,074	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/21 15:02
S14 4	7558	circuit adj board and insulating adj substrate	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/21 15:40
S14 5	72	S144 and capacitor adj structure	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/21 17:28
S14 6	2	2004/0160751	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/21 17:29
S14 7	2	("20040160751").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/09/21 17:29
S14 8	8776	fixing adj mechanism	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/21 18:13

## EAST Search History

S14 9	151	S148 and printed adj circuit adj board	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/21 18:13
S15 0	14	S149 and chassis	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/21 18:13
S15 1	7	S150 and tray	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/21 18:13
S15 2	2	S151 and unclasp	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/21 18:14
S15 3	14	fixing adj mechanism and printed adj circuit adj board and chassis	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/21 18:16
S15 4	7	fixing adj mechanism and printed adj circuit adj board and chassis and tray	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/21 18:16
S15 5	2	fixing adj mechanism and printed adj circuit adj board and chassis and tray and unclasp	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/21 18:16
S15 6	0	361/801.ccls	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/21 18:15

## EAST Search History

S15 7	1070	361/801.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/21 18:15
S15 8	3	S148 and S157	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/21 18:15
S15 9	2	S148 and S149 and S157	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/21 18:15
S16 0	1	S148 and S149 and S150 and S151 and S157	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/21 18:15
S16 1	1	fixing adj mechanism and printed adj circuit adj board and chassis and fixing adj mechanism and printed adj circuit adj board and chassis and tray and 361/801.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/21 18:45
S16 2	1	fixing adj mechanism and printed adj circuit adj board and chassis and tray and unclasp and fixing adj mechanism and printed adj circuit adj board and chassis and fixing adj mechanism and printed adj circuit adj board and chassis and tray and 361/801.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/21 18:17
S16 3	4393	Measuring adj Ph	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/22 10:50
S16 4	29	S163 and animal adj tissue	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/22 10:54

## EAST Search History

S16 5	963	356/301.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/22 10:55
S16 6	2	S163 and 356/301.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/22 10:57
S16 7	518	light adj source and 356/301.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/22 10:58
S16 8	373	S167 and lens	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/22 10:58
S16 9	330	S168 and filter	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/22 10:58
S17 0	3	S169 and computing adj device	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/22 11:13
S17 1	30	"5,764,819"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/22 11:14
S17 2	173	spectrum and 356/301.ccls. and Uv and filter	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/22 11:16

## EAST Search History

S17 3	12	spectrum and 356/301.ccls. and Uv and filter and chemical adj substance	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/22 11:17
S17 4	0	("2005/0117150").URPN.	USPAT	OR	ON	2007/09/22 11:20
S17 5	8	ph near measurement and uv adj exposure	USPAT	OR	ON	2007/09/22 11:22
S17 6	231	flexible adj wiring adj substrate	USPAT	OR	ON	2007/09/22 11:22
S17 7	28	S176 and insulating adj substrate	USPAT	OR	ON	2007/09/22 11:23
S17 8	23	S177 and pattern	USPAT	OR	ON	2007/09/22 11:23
S17 9	16	S178 and solder	USPAT	OR	ON	2007/09/22 11:23
S18 0	0	S179 and tin near bismuth	USPAT	OR	ON	2007/09/22 11:24
S18 1	1	S179 and resist adj layer	USPAT	OR	ON	2007/09/22 11:28
S18 2	4	("308354 ").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/09/22 11:33
S18 3	0	("JP"308354" ").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/09/22 11:33
S18 4	760	flexible adj wiring adj substrate	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/24 09:42
S18 5	6576	flexible adj wiring	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/24 09:42

## EAST Search History

S18 6	220	S185 and insulating adj substrate	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/24 09:43
S18 7	1703	S185 and insulating	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/24 09:43
S18 8	453	S187 and wiring adj pattern	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/24 09:43
S18 9	237	S188 and solder	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/24 09:44
S19 0	7	S189 and tin adj plating adj layer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/24 10:18
S19 1	7	"6572780"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/24 09:54
S19 2	2	("6572780").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/09/24 11:07

## EAST Search History

S19 3	32	("20030038379"   "20030091842"   "20030145949"   "20050205972"   "3503782"   "3554835"   "5073422"   "5082706"   "5273805"   "5281455"   "5759455"   "5965226"   "6210767"   "6280831"   "6280851"   "6320135"   "6441474"   "6458234"   "6476330"   "6521309"   "6548234"   "6572780"   "6605369"   "6613987"   "6617521"   "6624520"   "6761948"   "6794031"   "6900989"   "6911729").PN. OR ("7173322"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/09/24 09:58
S19 4	563	257/702.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/24 10:22
S19 5	0	S193 and S194	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/24 10:23
S19 6	0	S195 and S194	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/24 10:23
S19 7	3	S185 and S194	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/24 10:23
S19 8	0	("2006/0163718").URPN.	USPAT	OR	ON	2007/09/24 10:24
S19 9	19	("5300402"   "5477160"   "5508229"   "5518964"   "5677576"   "5691041"   "5834844"   "5892271"   "5915170"   "5933712"   "5936843"   "5990546"   "6002168"   "6020220"   "6077757"   "6081026"   "6323058").PN. OR ("6900532").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/09/24 10:24
S20 0	0	("2006/0163718").URPN.	USPAT	OR	ON	2007/09/24 10:31

## EAST Search History

S20 1	0	("flexibleadjwiringadjsubstrate").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/09/24 11:07
S20 2	760	flexible adj wiring adj substrate	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/24 11:07
S20 3	56	S202 and insulating adj substrate	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/24 11:08
S20 4	17	S203 and wiring adj pattern	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/24 11:43
S20 5	2	S204 and solder adj resist adj layer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/24 11:20
S20 6	2	("2002195043").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/09/24 11:10
S20 7	43	S203 and pattern	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/24 11:20
S20 8	2	S207 and solder adj resist adj layer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/24 11:20

## EAST Search History

S209	26	S207 and solder	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/24 11:30
S210	2	S209 and tin-bismuth adj alloy	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/24 11:27
S211	9	S209 and alloy	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/24 11:27
S212	760	flexible adj wiring adj substrate	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/24 11:43
S213	433	S212 and pattern	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/24 11:43
S214	339	S213 and thickness	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/24 11:46
S215	1	S214 and alloy adj plating adj layer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/24 11:46
S216	1	S214 and alloy adj plating	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/24 11:46

## EAST Search History

S21 7	183	S214 and solder	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/24 11:52
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